

TUESDAY SEPTEMBER 16 <sup>th</sup>
14.00 - 20.00 Registration
18.00 - 20.00 Supper

WEDNESDAY SEPTEMBER 17 <sup>th</sup>
8.30 - 9.30 Breakfast
9.30 - 9.45 Opening ceremony
9.45 - 11.00 Plenary session A
9.45 - 10.10 <b>Zdzisław Filus</b> <i>Institute of Electronics at the Silesian University of Technology</i>
10.10 - 10.35 <b>Peter J. Gielisse, Malgorzata Jakubowska, Halina Niculescu</b> <i>The Role of Nanomaterials in Future Microelectronics</i>
10.35 - 11.00 <b>Marko Hrovat, Darko Belavic, Janez Holc, Janez Bernard, Andreja Bencan</b> <i>The Investigation of Thick Film Resistors Fired at Different Temperatures</i>
11.00 - 11.50 Coffee break
11.50 - 13.30 Plenary session B
11.50 - 12.15 <b>Karlheinz Bock, Rolf Aschenbrenner, Jan Felba</b> <i>Polymer Electronics - Fancy or the Future of Electronics</i>
12.15 - 12.40 <b>Ryszard Kisiel</b> <i>Trends in Soldering Process for Advanced Microelectronics Assembly</i>
12.40 - 13.05 <b>Andrzej Dziedzic, Adam Janik, Andrzej Kolek, Waleed Ehrhardt, Heiko Thust</b> <i>Advanced Electrical and Stability Characterisation of Untrimmed and Pulse Voltage or Laser - Trimmed Thick Film Resistors</i>
13.05 - 13.30 <b>Khalil Arshak, David Egan</b> <i>The Development of Methods and Materials for the Production of Planar Transformers Using Thick-Film Technology</i>
13.15 - 15.00 Lunch
15.00 - 17.00 Poster session I
17.00 - 18.00 IMAPS Members Meeting
19.30 - Grill Party

THURSDAY SEPTEMBER 18 <sup>th</sup>
8.30 - 9.30 Breakfast
9.45 - 11.00 Plenary session C
9.45 - 10.10 <b>Bogusława Adamowicz, Hideki Hasegawa</b> <i>Characterization of the Electronic Status of III-V-based Surface and Interfaces for Nanoelectronics Applications</i>
10.10 - 10.35 <b>Gert Winkler, Gernot Bischoff, Aneta Sutor</b> <i>New Materials and Technologies for Printed Circuit Boards</i>
10.35 - 11.00 <b>Grażyna Beensh-Marchwicka, Eugeniusz Prociów, Stanisław Osadnik</b> <i>Materials for Thin-Film Thermal Converters</i>
11.00 - 11.25 <b>Khalil Arshak, Olga Korostynska, John Henry</b> <i>Response of Indium Oxide and Silicon Oxide Thick Film PN-Junctions to Gamma Radiation Exposure</i>
11.25 - 12.00 Coffee break
12.00 - 14.00 Poster session II
14.00 - 15.00 Lunch
15.30 - 19.00 A tour
19.30 - Gala dinner

FRIDAY SEPTEMBER 19 <sup>th</sup>
8.30 - 9.30 Breakfast
10.00 - 11.00 Workshop "Photovoltaic Cells" (in Polish)
10.00 - 10.30 <b>Marek Lipiński, Piotr Panek</b> <i>Optimisation of multicrystalline silicon solar cell</i>
10.30 - 11.00 <b>Piotr Panek, Elżbieta Bielańska, Jan Dutkiewicz</b> <i>The Effect of Porous Silicon Layer on Solar Cells</i>
11.00 - 11.30 Coffee break
11.30 - 12.30 Workshop "Photovoltaic Cells" (in Polish)
11.30 - 12.00 <b>Kazimierz Drabczyk</b> <i>Solar Cell Emitter Layer Created During Diffusion in IR Belt Furnace, Carried Out with Pastes as Diffusion Source</i>
12.00 - 12.30 <b>Wojciech Grzesiak, Michał Cieź, Jerzy Początek, Wiesław Zaraska, Krzysztof Wietrzny, Jan Koprowski</b> <i>Photovoltaic Systems as the clean energy source for the present and for to-morrow</i>
12.45 - 14.00 Lunch

<b>WEDNESDAY SEPTEMBER 17<sup>th</sup></b>	<b>Poster session I</b>
1. <i>Defect and material analysis of IC's interconnections using laser ultrasonics</i>	<b>G. Andriamonje, Y. Ousten</b>
2. <i>Quantitative investigation of adhesion in thyristor structure using thermal wave method and evolutionary algorithm</i>	<b>Robert Arsoba , Zbigniew Suszyński</b>
3. <i>Modelling of 3d Multisubstrate Structures</i>	<b>Jindřich Bulva, Ivan Szendiuch</b>
4. <i>Heat transfer analysis in thick-film multilayer systems using electro – thermal analogy</i>	<b>Grzegorz Bład, Zenon Hotra, Dariusz Klepacki, Jerzy Potencki, Mariusz Węglarski</b>
5. <i>Analysis of photovoltaic cell emitter layer using diffusion process simulation</i>	<b>Wojciech Filipowski , Kazimierz Drabczyk, Krzysztof Waczyński</b>
6. <i>Complete solar systems of output equipped with 230v 50hz dc/ac inverters</i>	<b>Wojciech Grzesiak, Jerzy Poczatek, Krzysztof Witek Krzysztof Wietrzny, Jan Koprowski</b>
7. <i>Solar home station systems</i>	<b>W.Grzesiak, J.Poczatek, W.Zaraska, K.Wietrzny</b>
8. <i>Contribution to uv laser ablation process of sound PCB microvias</i>	<b>Halina Hackiewicz, Grażyna Koziol, Janusz Borecki</b>
9. <i>Measurements of thermal transients in semiconductor devices in the internal or external power excitation mode</i>	<b>Włodzimierz Janke, Jarosław Kraśniewski, Mariusz Kraśniewski, Maciej Oleksy, Jerzy Mizeraczyk, Marek Kocik</b>
10. <i>Conditions of passive tag supply in RFID systems</i>	<b>Piotr Jankowski-Mihulowicz, Włodzimierz Kalita</b>
11. <i>Programme SCAN BOND 1.0 - new instrument for visual inspection of wire bonds</i>	<b>Ryszard Jezior , Włodzimierz Lukasik , Sebastian Dlugon</b>
12. <i>Optical Method of TGSL10 Single Crystals Pre-selection. Method Uncertainty</i>	<b>Włodzimierz Kalita, Mariusz Trybus, Władysław Proszak</b>

13. <i>Preliminary Results of Conductive Adhesive Fillet Resistance Stability in Double Sided PCBs</i>	<b>Ryszard Kisiel, Artur Markowski</b>
14. <i>Virtual laboratory PACK in Java/Flash for research the semiconductor materials</i>	<b>A. Patryn, W. Suslow, R. Kierecki</b>
15. <i>Correlation Between Domain Structure And Electric Permeability of TGSL10 Single Crystals</i>	<b>Władysław Proszak</b>
16. <i>Optoelectronic gate realizing the function wired NOR</i>	<b>Z. Porada, E. Schabowska-Osiowska</b>
17. <i>A new approach to evaluation of the quality of bushings</i>	<b>Zbigniew Suszyński, Piotr Majchrzak</b>
18. <i>Photoacoustic investigation of the quality of metal-glaze bonding for harmonic and pulse excitation</i>	<b>Zbigniew Suszyński, Piotr Majchrzak</b>
19. <i>The idea of thermal wave contrast images in analysis of thermal properties of solids</i>	<b>Zbigniew Suszyński , Piotr Majchrzak</b>
20. <i>Usage of pulse excitation in photo-thermal investigation of high power thyristor structure</i>	<b>Zbigniew Suszyński, Radosław Duer, Robert Arsoba</b>
21. <i>Simplified flip chip solder bonding on FR-4 laminate</i>	<b>Zbigniew Szczepański</b>
22. <i>Photosensitivity and transport phenomena of solar cells</i>	<b>P. Wojcik, T. Stapinski, T. Pisarkiewicz</b>
23. <i>Improved top-hat and u-shaped resistors for high precision laser trimming</i>	<b>Marek Wroński</b>
24. <i>Influence of soldering oven temperature profile on the quality of PB-free solder joints</i>	<b>Wiesław Zaraska, Krzysztof Witek, Michał Cież, Ryszard Knapik</b>
25. <i>Computer program for simulation of 3-d shapes fabricated in silicon anisotropic etching process</i>	<b>I. Zubel, M. Kramkowska, P. Wójcik</b>
26. <i>Possibilities of spatial shapes modification by silicon anisotropic etching</i>	<b>I. Zubel, M. Kramkowska</b>

THURSDAY SEPTEMBER 18 <sup>th</sup> Poster session II
1. <i>Characterization of Si-Ta thin film materials with high Ta content</i> <b>Grażyna Beensh-Marchwicka, Eugeniusz Prociów</b>
2. <i>Evaluation of silver alloys for thermosonic assembly of microelectronics circuits</i> <b>Andrzej Bochenek, Barbara Bober, Bronisława Olszewska-Mateja, Zbigniew Żaluk</b>
3. <i>Application of lead-free solder paste for soldering of PCB's</i> <b>Krystyna Bukat, Janusz Sitek, Andrzej Jaworski, Dubravka Ročak, Darko Belavič, Janeta Faifar-Plut</b>
4. <i>Comparison of electrooptical parameters in electroluminescent structures composed with various transparent electrodes</i> <b>Michał Cieź, Marek A. Łukasik, Krzysztof Witek, Wiesław Zaraska</b>
5. <i>Correlation between geometry and electrical properties of LTCC and thick-film microresistors</i> <b>Andrzej Dzedzic, Edward Miś, Lars Rebenklau, Klaus-Jurgen Wolter</b>
6. <i>Thick-film and LTCC resistors under high hydrostatic pressure</i> <b>Andrzej Dzedzic, Ryszard Poprawski, Andrzej Kolarz</b>
7. <i>On the Design and Fabrication of Photoimageable Thick-Film Multilayer Filters and couplers</i> <b>Barbara Dziurdzia, Zbigniew Magoński, Stanisław Nowak, Michał Cieź, Wojciech Gregorczyk, Waclaw Niemyjski</b>
8. <i>Thick film pastes based on perovskite materials with addition of platinum</i> <b>Joanna Gandurska, Irena Śnieżyńska, Anna Marek</b>
9. <i>ZnO LTCC varistors</i> <b>Katarzyna Majewska, Leszek J. Golonka, Johanna Honkamo, Heli Jantunen, Witold Mielcarek</b>
10. <i>Electrical and stability properties of molybdenum oxide based thick film resistors</i> <b>Małgorzata Jakubowska, Jerzy Kalenik, Anna Miecznik, Elżbieta Zwierkowska</b>
11. <i>Application of ceria electrolyte in electrocatalytic gas sensor</i> <b>Grzegorz Jasiński, Piotr Jasiński, Bogdan Chachulski, Antoni Nowakowski</b>

12. <i>Ni-P-B resistive layer obtained by chemical method</i> <b>Piotr Kowalik, Zbigniew Pruszowski</b>
13. <i>Dielectric Properties of Lead-free Ferroelectric Perovskites Based on Calcium</i> <b>J. Kulawik, D. Szwagierczak, J. Gandurska, A. Marek, I. Śnieżyńska</b>
14. <i>Carbon-polymer resistors heating layer on enamelled steel substrates</i> <b>Łukasik Andrzej, Nowak Stanisław, Siwulski Stanisław</b>
15. <i>Influence of filler quantity on thermal characteristics of carbon-acrylic resistive layers</i> <b>Andrzej Łukasik, Zbigniew Pruszowski</b>
16. <i>Polymer-carbon-aluminium resistive activation layers in the process of chemical ni-p metallisation</i> <b>Andrzej Łukasik, Michał Cieź, Zbigniew Pruszowski</b>
17. <i>Properties of thick-film resistors on dielectric and metal substrates for piezoresistive sensors</i> <b>Thomas Mader, Claudio Grimaldi, Peter Ryser</b>
18. <i>Gas microsensor based on semiconductors deposited onto silicon membrane</i> <b>T. Pisarkiewicz, W. Maziarz, J. Koszur, J. Jazwinski, J.M. Łysko</b>
19. <i>Cadmium Sulphide Thin Films For Photovoltaic Applications</i> <b>E. Schabowska-Osiowska, T. Pisarkiewicz, T. Kenig</b>
20. <i>Investigation of profile of thermal properties in copper-ceramics structures</i> <b>Zbigniew Suszyński, Piotr Majchrzak</b>
21. <i>Amorphous silicon-carbon as a new material for optoelectronic applications</i> <b>B. Swatowska and T. Stapinski</b>
22. <i>Aging behavior of capacitors with relaxor dielectrics</i> <b>D. Szwagierczak, J. Kulawik, S. Nowak, J. Gandurska, A. Marek, I. Śnieżyńska, B. Gröger</b>
23. <i>Investigation of Pb-free Sn-Ag-Cu alloy shear strength under influence of environmental conditions</i> <b>Krzysztof Witek, Michał Cieź, Wiesław Zaraska, Wojciech Grzesiak</b>